

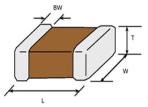
Specification of Automotive MLCC (Reference sheet)



- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL10B105KA8VPNC
- Description : CAP, 1/F, 25V, ± 10%, X7R, 0603
- AEC-Q200 Qualified

A. Dimension

Dimension



Size	0603 inch
L	1.6±0.1 mm
W	0.8±0.1 mm
Т	0.8±0.1 mm
BW	0.3±0.2 mm

B. Samsung Part Number

<u>CL</u>	<u>10</u>	<u>B</u>	<u>105</u>	<u>ĸ</u>	A	<u>8</u>	v	<u>P</u>	<u>N</u>	<u>c</u>
1	2	3	4	5	6	(\bar{D})	8	9	10	1

① Series	Samsung Multi-layer Ceramic	Capacitor	
 Size 	0603 (inch code)	L: 1.6±0.1 mm	W: 0.8±0.1 mm
③ Dielectric	X7R	Inner electrode	Ni
④ Capacitance	1 <i>μ</i> F	Termination	Soft termination
5 Capacitance	± 10%	Plating	Sn 100% (Pb Free)
tolerance		Product	Automotive
Rated Voltage	25 V	Special code	Normal
⑦ Thickness	0.8±0.1 mm	① Packaging	Cardboard Type, 7" Reel

C. Reliability Test and Judgement condition

Test items	Performance	Test condition				
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1,000hrs @ Max. temperature				
Exposure	Capacitance Change: Within ±10 %	Measurement at 24±2hrs after test conclusion				
	Tan δ : 0.125 max.					
	IR : More than 10,000 M $^{\Omega}$ or 500 M $^{\Omega}$ × μ F	Initial Measurement 2*				
	Whichever is smaller	Final Measurement 3*				
Temperature Cycling	Appearance : No abnormal exterior appearance	1,000Cycles				
	Capacitance Change: Within ±10 %	Initial Measurement 2*				
	Tan δ : 0.125 max.	Final Measurement 3*				
	IR: More than 10,000 ^M ♀ or 500 ^M ♀× <i>µ</i> F	Measurement at 24±2hrs after test conclusion				
	Whichever is smaller	1 cycle condition : -55+0/-3 $^{\circ}$ C(30±3min) → Room Temp. (1min)				
		→ 125+3/-0 \degree (30±3min) → Room Temp. (1min)				
Destructive Physical	No Defects or abnormalities	Per EIA 469				
Analysis						
Humidity Bias	Appearance : No abnormal exterior appearance	1,000hrs 85°C/85%RH, Rated Voltage and 1.3~1.5V,				
	Capacitance Change : Within ±12.5 %	Add 100kohm resistor				
	Tan δ : 0.125 max.	Initial Measurement 2*				
	IR : More than 500 № or 25 №×µF	Final Measurement 4*				
	Whichever is smaller	Measurement at 24±2hrs after test conclusion				
		The charge/discharge current is less than 50mA.				
High Temperature	Appearance : No abnormal exterior appearance	1,000hrs @ 125℃, 150% Rated Voltage,				
Operating Life	Capacitance Change : Within ±12.5 %	Initial Measurement 2*				
-	Tan δ : 0.125 max.	Final Measurement 4*				
	IR : More than 1,000 № or 50 №×µF	Measurement at 24±2hrs after test conclusion				
	Whichever is smaller	The charge/discharge current is less than 50mA.				

	Performance			1	est conditi	on			
External Visual	No abnormal exterior appearance	Mic	roscope ('10)						
Physical Dimensions	Within the specified dimensions	Using The calipers							
Mechanical Shock	Appearance : No abnormal exterior appearance	Thre	ee shocks in ea	ach directior	n should be	applied along			
	Capacitance Change : Within ±10 %	3 m	utually perpend	dicular axes	of the test s	pecimen (18 sh	ocks)		
	Tan δ, IR: Initial spec.	Peak value Duration Wave Velocity							
			1,500G	0.5ms	Half sine	4.7m/sec			
		Initia	al Measuremer	nt 2*]		
		Fina	Final Measurement 5*						
Vibration	pearance : No abnormal exterior appearance 5g's for 20min., 12cycles each of 3 orientations,								
- Ibitation	Capacitance Change : Within ±10 %	Use 8"×5" PCB 0.031" Thick 7 secure points on one long side							
	Tan δ, IR : Initial spec.	and 2 secure points at corners of opposite sides. Parts mounted							
			within 2" from any secure point. Test from 10~2,000Hz.						
		Initial Measurement 2*							
		Final Measurement 5*							
Resistance to	Appearance : No abnormal exterior appearance	_			222				
Solder Heat	Capacitance Change : Within ±10 %		preheating : 150℃ for 60~120 sec. Solder pot : 260±5℃, 10±1sec.						
	Tan δ, IR: Initial spec.		Initial Measurement 2*						
			Final Measurement 3*						
ESD	Appearance : No abnormal exterior appearance		AEC-Q200-002 or ISO/DIS10605						
230	Capacitance Change : Within ±10 %	Initial Measurement 2*							
	Tan δ, IR : Initial spec.	Final Measurement 4*							
Solderability	95% of the terminations is to be soldered	a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245±5°C							
,	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245 \pm 5 $^\circ$ C							
		c) S	c) Steam aging for 8 hours, Immerse in solder for 120s at 260 ± 5 °C						
		solder : a solution ethanol and rosin							
Electrical	Capacitance : Within specified tolerance	*A c	apacitor prior t	o measuring	g the capaci	tance is heat tre	ated at		
Characterization	Tan δ : 0.1 max.	150	150 +0/-10 $^{\circ}$ for 1hour and maintained in ambient air for 24±2 hours						
	IR(25℃): More than 10,000 ^M or 500 ^M ×µF	The Capacitance / D.F. should be measured at 25 $^\circ\!\!\!\!^\circ\!\!\!^\circ$,							
	Whichever is smaller	1 k ^l z ± 10%, 1 ± 0.2 Vrms							
	IR(125℃): More than 1,000 ^M or 10 ^M × <i>µ</i> F	I.R. should be measured with a DC voltage not exceeding							
	Whichever is smaller	Rated Voltage @25℃, @125℃ for 60~120 sec.							
	Dielectric Strength	Diel	ectric Strength	: 250% of t	he rated volf	age for 1~5 sec	onds		
Board Flex	Appearance : No abnormal exterior appearance	Bending to the limit, 3 mm for 60 seconds 1*				•			
	Capacitance Change : Within ±10 %	Initial Measurement 2*							
	_	Final Measurement 5*							
Terminal	Appearance : No abnormal exterior appearance	10 N, for 60 sec.							
Strength(SMD)	Capacitance Change : Within ±10 %	Initial Measurement 2*							
	_	Fina	Final Measurement 5*						
Beam Load	Destruction value should be exceed 20 N	Bea	m speed 0.5±0	0.05 mm/sec					
Temperature	X7R								
Characteristics	From -55 ℃ to 125 ℃, Capacitance change should	l be wi	thin ±15%						
0.10100101131103									

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260 +0/-5 °C, 30sec.), Meet IPC/JEDEC J-STD-020 D Standard

- *1 : The figure indicates typical specification. Please refer to individual specifications.
- *2 : Initial measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- *3 : Final measurement : Let sit for 24±2 hours at room temperature after test conclusion, then measure.
- *4 : Final measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- *5 : Final measurement : Let measure within 24 hours at room temperature after test conclusion.

A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

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- ② Medical equipment
- *③ Military equipment*
- ④ Disaster prevention/crime prevention equipment
- *5* Power plant control equipment
- 6 Atomic energy-related equipment
- ⑦ Undersea equipment
- ⑧ Traffic signal equipment
- Data-processing equipment
- 10 Electric heating apparatus, burning equipment
- ${\it I\!\! D}$ Safety equipment
- 2 Any other applications with the same as or similar complexity or reliability to the applications